Contribution ID: **10**　　Type: **not specified**

Sensor design and Interconnects

Tuesday 12 July 2016 11:00 (1h 50m)

Si and compound semiconductor sensor design (distances, implantation, interpixel capacitance), edgeless Si sensors. Interconnections: Bump bonding, TSV (types, processing steps, materials involved, etc.)

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Session Classification: X-ray and charged particle detectors